A） Publications:

1. "Electromigration study in SnAg3.8Cu0.7 Solder Joints on Ti/Cr-Cu/Cu Under Bump Metallization"', YC Hsu, TL Shao, CJ Yang, Chih Chen, J. Elec. Mat., 32, 11,

2. "Threshold Current Density of Electromigration in Eutectic SPb Solder", YT Yeh, CK Chou, YC Hsu, Chih Chen, King-Ning Tu, Appl. Phys. Lett., 86

3. "Electromigration in Pb-free SnAg3.8CuO.7 Solder Stripes", YC Hsu, CK Chou, PC Liu, Chih Chen, DJ Yao, T Chou, King-Ning Tu, J. Appl. Phys., 98, 033523

4. "Measurement of Electromigration Parameters of Lead-free SnAg3.5 Solder Using V-groove Lines", ", YC Hsu, DS Chen, PC Liu, Chih Chen, J. Mater. Res.,

5. "Interfacial Reaction and Shear Strength of Pb-free SnAg2.5Cu0.8Sb0.5 and

SnAg3.0Cu0.5Sb0.2 Solder Bumps on Au/Ni(P) Metallization", YC Hsu, YM Huang, Chih Chen, Henry Wang, J. Alloy and Compound, 417, 180 (2006).

6. Study of electromigration in eutectic SPb solder stripes using the edge displacement method, CK Chou, YC Hsu Chih Chen. Journal of Electronic Materials 35(8):1655-

1659(2006)

（B）Industrial Cooperation：

1 . Lam Research universities research collaboration:

- Highly (111)-oriented Nanotwinned Cu for Redistribution Lines in InFO with High Electromigration Resistance. National Chiao Tung University, Materials Science and Engineering. Pro. Chih Chen and YC Hsu, 2019.

2. Federated Learning for Predictive Semiconductor Chambers Maintenance under IP-Protection Guarantees. National Yang-Ming Chiao Tung University. Electronic and Computer Engineering. Pro. Stefano Rini, Jay Chang and YC HSU , 2023.

3. Lam Research and Nanya Technology collaboration:

- Low Temperature and Fine Pitch Nanocrystalline Cu/SiCN Wafer-to-Wafer Hybrid Bonding. Electronic Component Technology Conference (ECTC) 2023.